

**Feature**

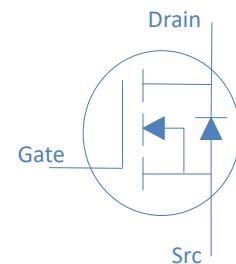
- ◊ High Speed Power Switching
- ◊ Enhanced Body diode dv/dt capability
- ◊ Enhanced Avalanche Ruggedness
- ◊ 100% UIS Tested, 100% Rg Tested
- ◊ Lead Free

**Application**

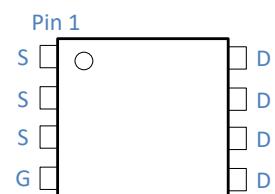
- ◊ Synchronous Rectification in SMPS
- ◊ Hard Switching and High Speed Circuit
- ◊ Power Tools
- ◊ UPS
- ◊ Motor Control

**100V N-Ch Power MOSFET**

$V_{DS}$	100	V
$R_{DS(on),typ}$	3.1	$m\Omega$
$I_D$ (Silicon Limited)	144	A
$I_D$ (Package Limited)	60	A


**DFN5x6**


Part Number	Package	Marking
HGN035N10A	DFN5x6	GN035N10A


**Absolute Maximum Ratings at  $T_j=25^\circ C$  (unless otherwise specified)**

Parameter	Symbol	Conditions	Value	Unit
Continuous Drain Current (Silicon Limited)	$I_D$	$T_C=25^\circ C$	144	A
Continuous Drain Current (Package Limited)		$T_C=100^\circ C$	91	
		$T_C=25^\circ C$	60	
Drain to Source Voltage	$V_{DS}$	-	100	V
Gate to Source Voltage	$V_{GS}$	-	$\pm 20$	V
Pulsed Drain Current	$I_{DM}$	-	520	A
Avalanche Energy, Single Pulse	$E_{AS}$	$L=0.1mH, T_C=25^\circ C$	180	mJ
Power Dissipation	$P_D$	$T_C=25^\circ C$	144	W
Operating and Storage Temperature	$T_J, T_{stg}$	-	-55 to 150	°C

**Absolute Maximum Ratings**

Parameter	Symbol	Max	Unit
Thermal Resistance Junction-Case	$R_{\Theta JC}$	0.87	°C/W
Thermal Resistance Junction-Ambient	$R_{\Theta JA}$	55	°C/W

**Electrical Characteristics at  $T_j=25^\circ\text{C}$  (unless otherwise specified)**
**Static Characteristics**

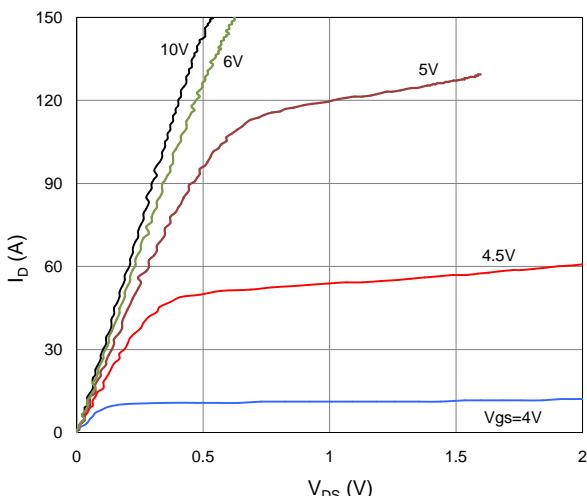
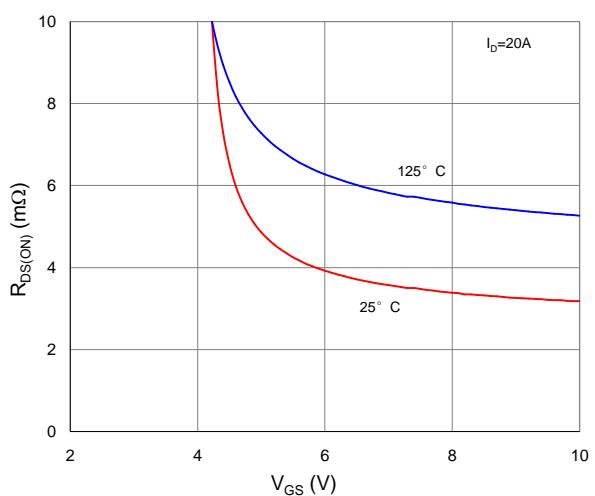
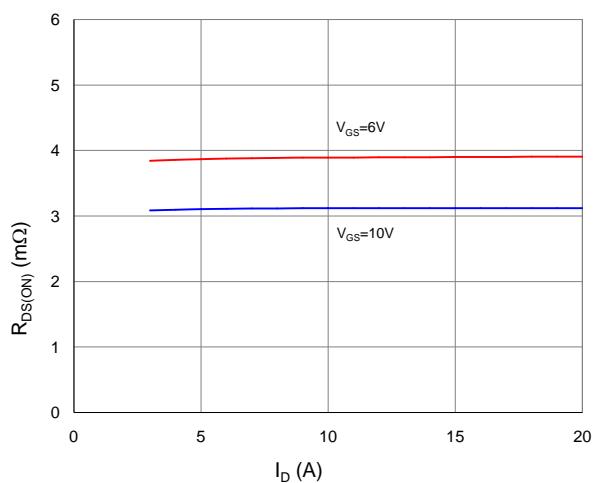
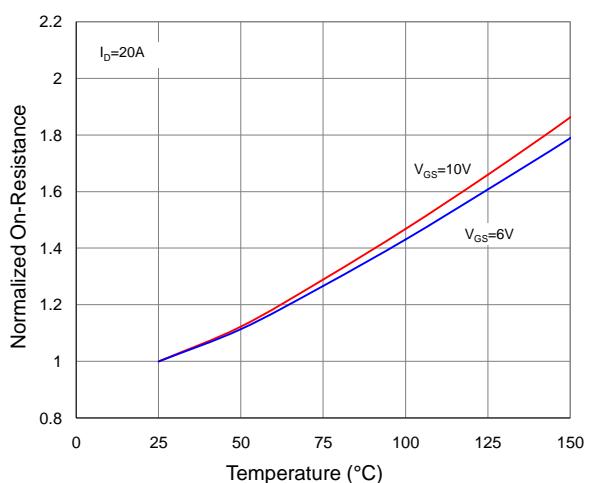
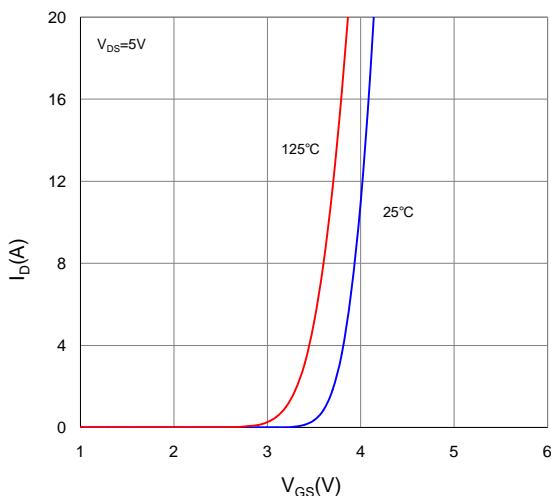
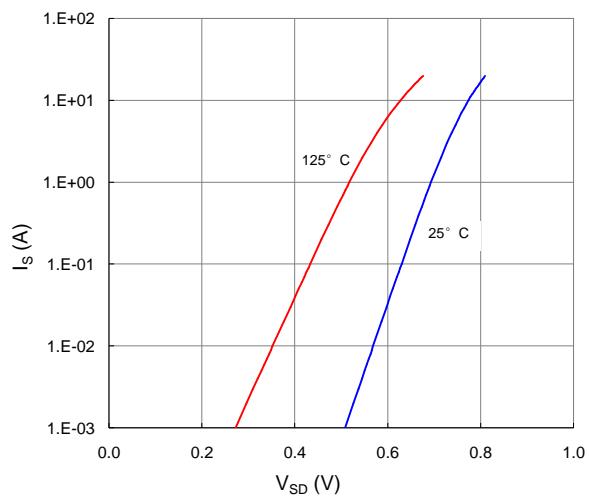
Parameter	Symbol	Conditions	Value			Unit
			min	typ	max	
Drain to Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}}=0\text{V}, I_D=250\mu\text{A}$	100	-	-	V
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{GS}}=V_{\text{DS}}, I_D=250\mu\text{A}$	2	2.8	4	
Zero Gate Voltage Drain Current	$I_{\text{DSS}}$	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=100\text{V}, T_j=25^\circ\text{C}$	-	-	1	$\mu\text{A}$
		$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=100\text{V}, T_j=100^\circ\text{C}$	-	-	100	
Gate to Source Leakage Current	$I_{\text{GSS}}$	$V_{\text{GS}}=\pm 20\text{V}, V_{\text{DS}}=0\text{V}$	-	-	$\pm 100$	nA
Drain to Source on Resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}}=10\text{V}, I_D=20\text{A}$	-	3.1	3.7	$\text{m}\Omega$
Transconductance	$g_{\text{fs}}$	$V_{\text{DS}}=5\text{V}, I_D=20\text{A}$	-	70	-	S
Gate Resistance	$R_G$	$V_{\text{GS}}=0\text{V}, V_{\text{DS}} \text{ Open}, f=1\text{MHz}$	-	0.6	-	$\Omega$

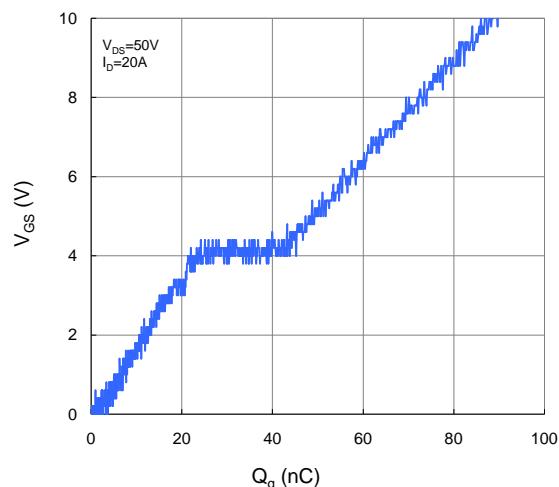
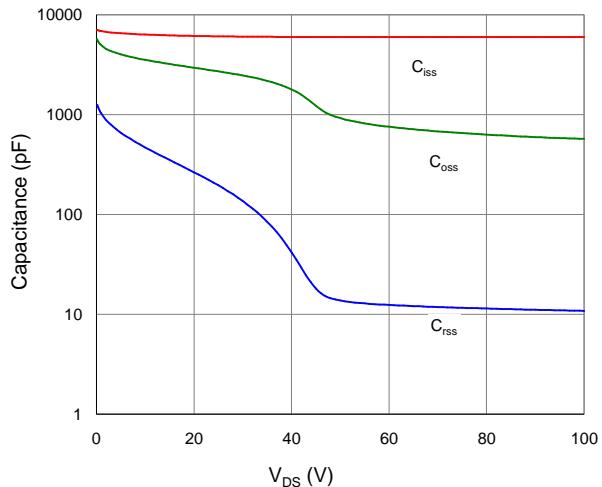
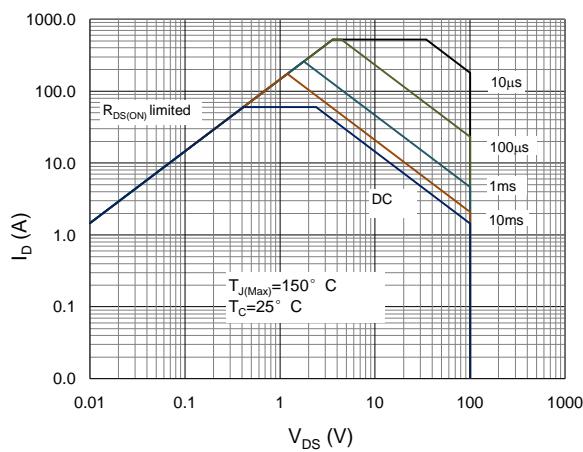
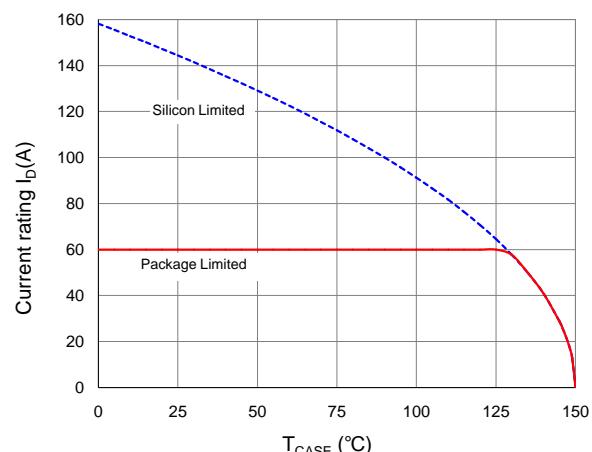
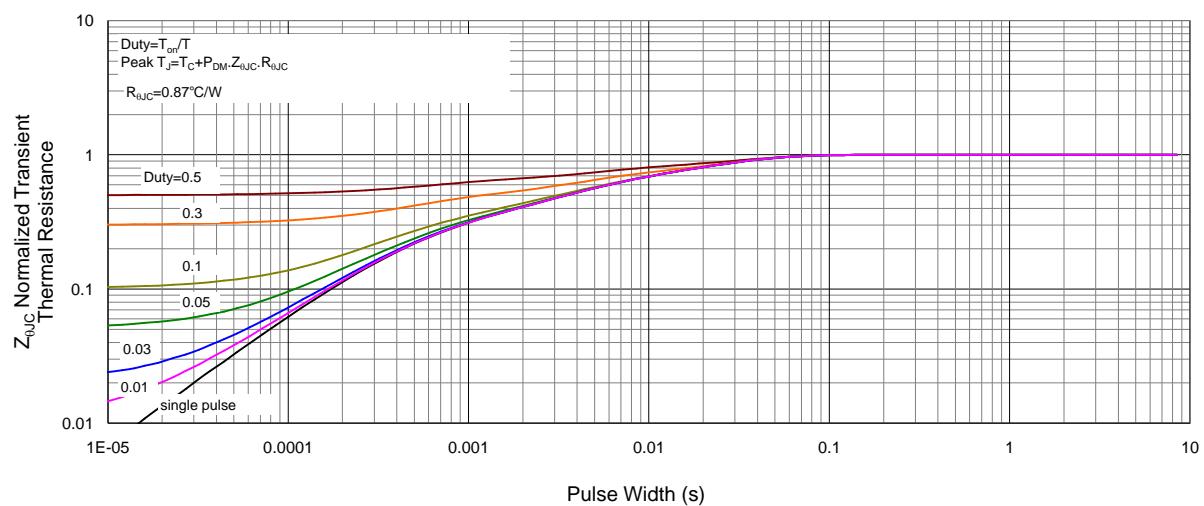
**Dynamic Characteristics**

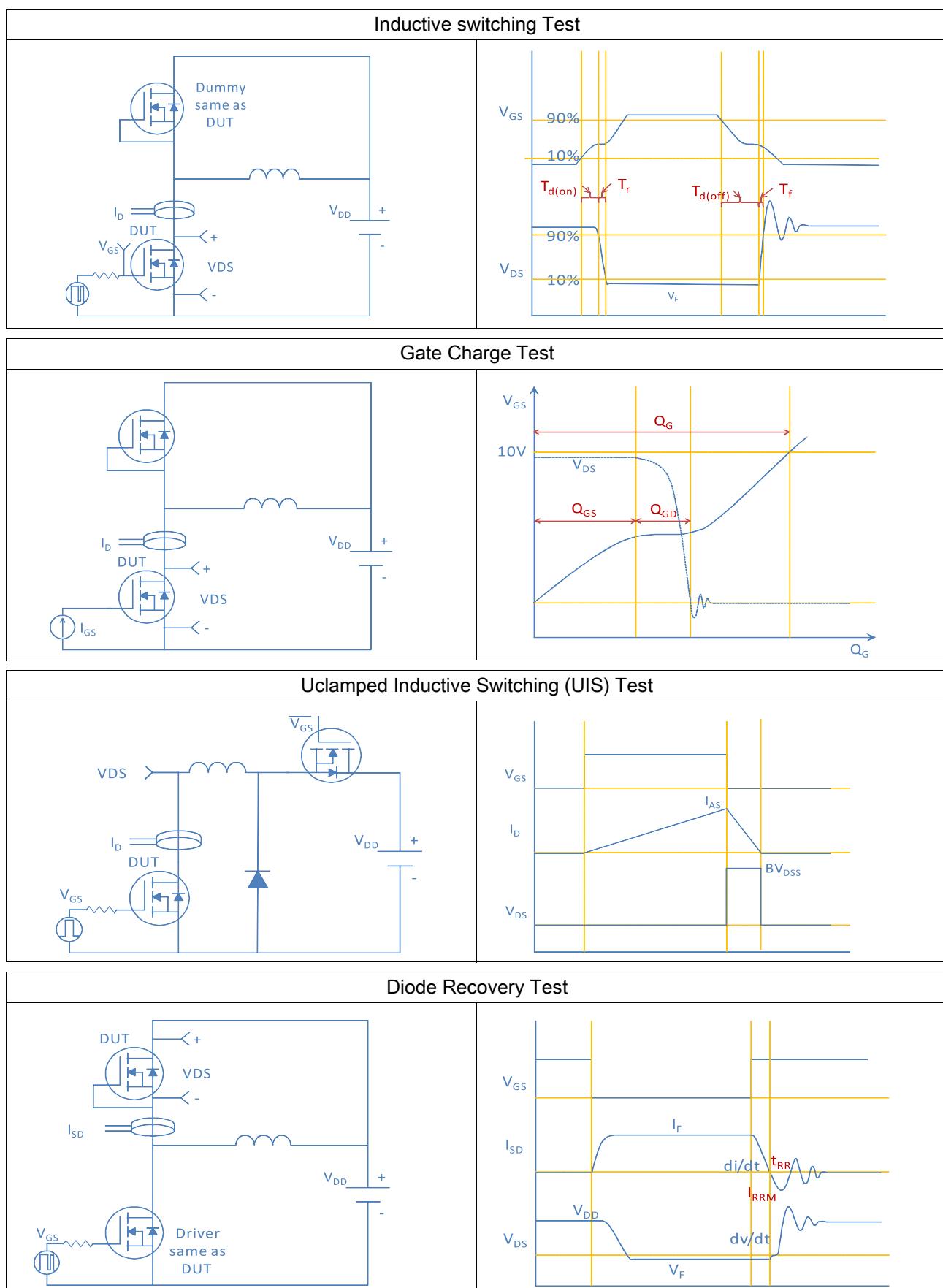
Input Capacitance	$C_{\text{iss}}$	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=50\text{V}, f=1\text{MHz}$	-	5995	-	pF
Output Capacitance	$C_{\text{oss}}$		-	923	-	
Reverse Transfer Capacitance	$C_{\text{rss}}$		-	13.8	-	
Total Gate Charge	$Q_g(10\text{V})$	$V_{\text{DD}}=50\text{V}, I_D=20\text{A}, V_{\text{GS}}=10\text{V}$	-	87	-	nC
Gate to Source Charge	$Q_{\text{gs}}$		-	22	-	
Gate to Drain (Miller) Charge	$Q_{\text{gd}}$		-	21	-	
Turn on Delay Time	$t_{\text{d}(\text{on})}$		-	24	-	
Rise time	$t_r$	$V_{\text{DD}}=50\text{V}, I_D=20\text{A}, V_{\text{GS}}=10\text{V}, R_G=10\Omega,$	-	18	-	ns
Turn off Delay Time	$t_{\text{d}(\text{off})}$		-	36	-	
Fall Time	$t_f$		-	9	-	

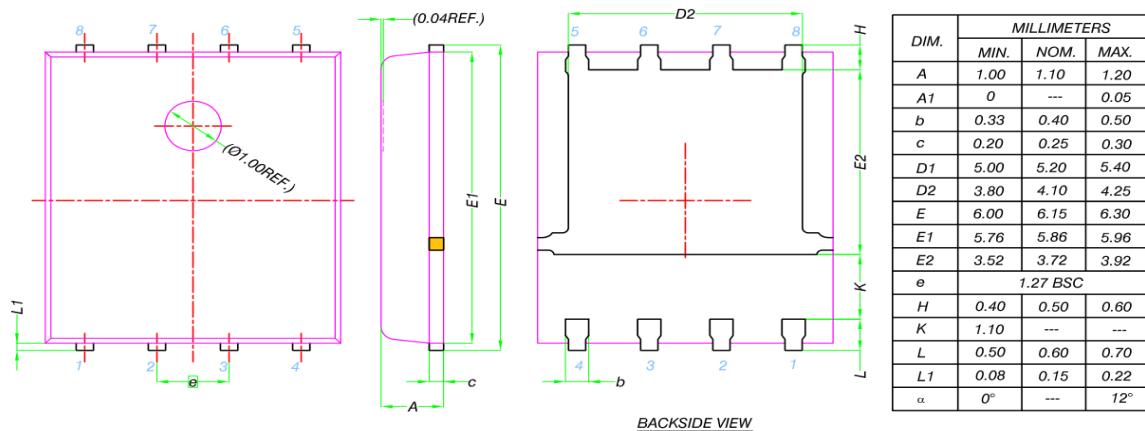
**Reverse Diode Characteristics**

Diode Forward Voltage	$V_{\text{SD}}$	$V_{\text{GS}}=0\text{V}, I_F=20\text{A}$	-	0.9	1.2	V
Reverse Recovery Time	$t_{\text{rr}}$	$V_R=50\text{V}, I_F=20\text{A}, dI_F/dt=100\text{A}/\mu\text{s}$	-	71	-	ns
Reverse Recovery Charge	$Q_{\text{rr}}$		-	114	-	nC

**Fig 1. Typical Output Characteristics**

**Figure 2. On-Resistance vs. Gate-Source Voltage**

**Figure 3. On-Resistance vs. Drain Current and Gate Voltage**

**Figure 4. Normalized On-Resistance vs. Junction Temperature**

**Figure 5. Typical Transfer Characteristics**

**Figure 6. Typical Source-Drain Diode Forward Voltage**


**Figure 7. Typical Gate-Charge vs. Gate-to-Source Voltage**

**Figure 8. Typical Capacitance vs. Drain-to-Source Voltage**

**Figure 9. Maximum Safe Operating Area**

**Figure 10. Maximum Drain Current vs. Case Temperature**

**Figure 11. Normalized Maximum Transient Thermal Impedance, Junction-to-Case**




**DFN5x6\_P, 8 Leads**


DIM.	MILLIMETERS		
	MIN.	NOM.	MAX.
A	1.00	1.10	1.20
A1	0	---	0.05
b	0.33	0.40	0.50
c	0.20	0.25	0.30
D1	5.00	5.20	5.40
D2	3.80	4.10	4.25
E	6.00	6.15	6.30
E1	5.76	5.86	5.96
E2	3.52	3.72	3.92
e	1.27 BSC		
H	0.40	0.50	0.60
K	1.10	---	---
L	0.50	0.60	0.70
L1	0.08	0.15	0.22
$\alpha$	0°	---	12°

